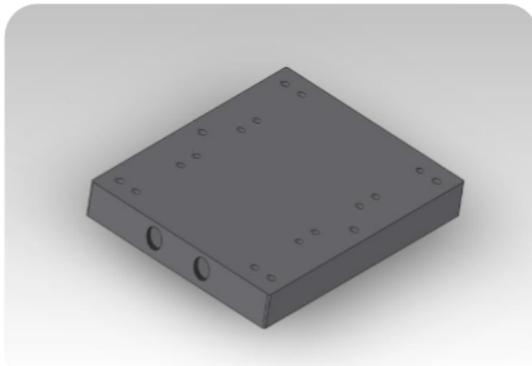




One step ahead in cooling!

STANDARD PT Zed 1421

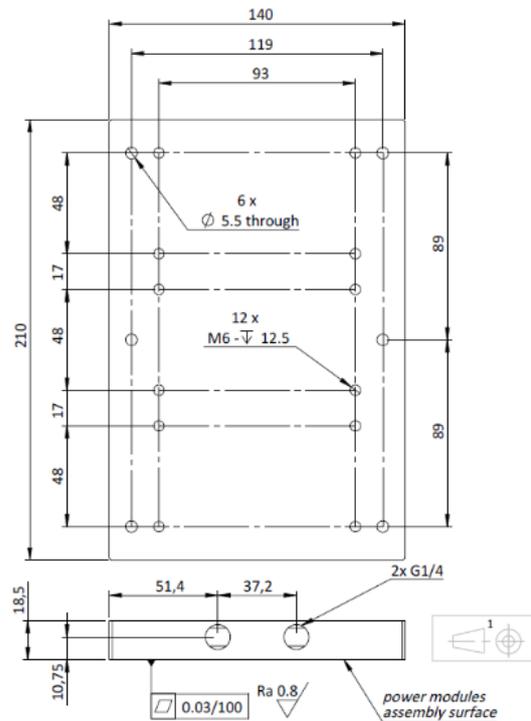


- ✓ **compact** (140 x 210 x 18.5 mm)
- ✓ **light** (1.3 kg)
- ✓ **efficient** ($R_{th} = 10 \text{ }^\circ\text{C/kW}$ @ 5 l/min)
- ✓ **safe and reliable** Leak free (100% tested @ 10 bar)

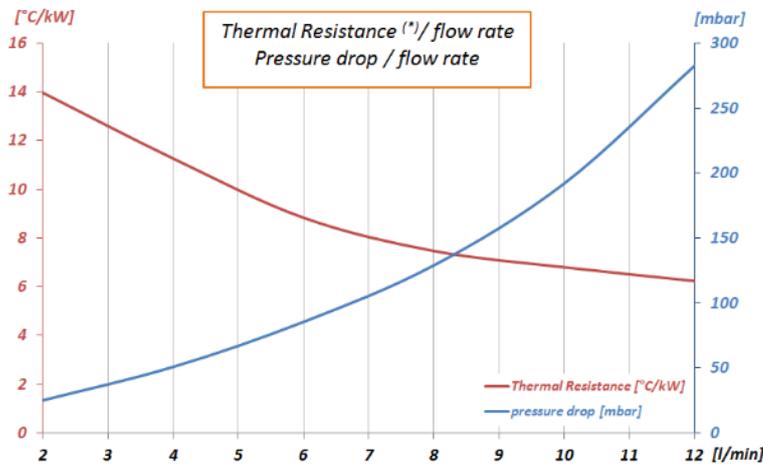
Materials: Aluminum alloy Al EN AW 6060 + turbulators inside

Cooling circuit 100% sealed by brazing under controlled atmosphere

Very uniform temperature distribution under power modules



- Compatible Power Module Packages:**
- ✓ MITSUBISHI 62mm Package
 - ✓ INFINEON 62mm Package
 - ✓ SEMIKRON SEMiTRANS[®] CaseD56
 - ✓ FUJI Semiconductor M127;M234;M235
 - ✓ MICROSEMI SP6, D3 and D4 Packages



Suitable for any high power semiconductor application

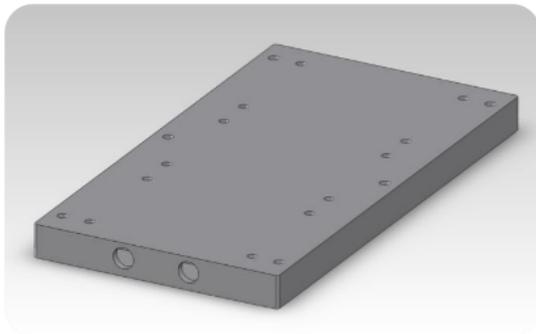


(*) Thermal Resistance: $\max T_{LCP \text{ surface}} \text{ to } T_{\text{fluid IN}}$ (Water + Ethylene Glycol 50%vol. @40 $^\circ\text{C}$)



One step ahead in cooling!

STANDARD PT Zed 1426

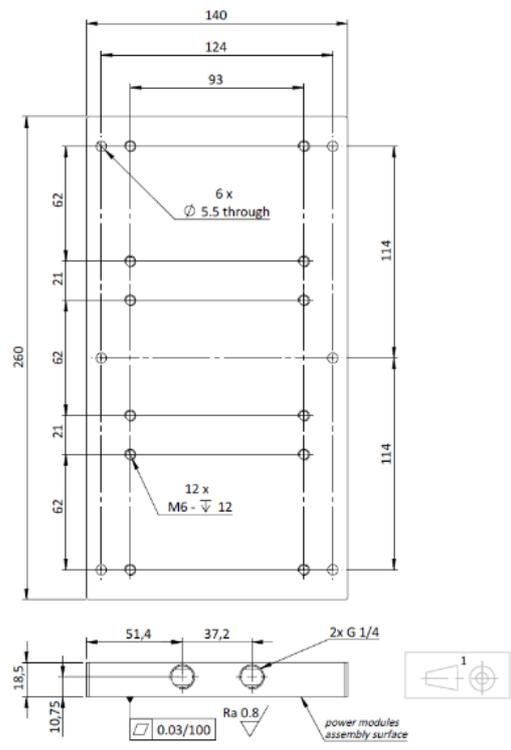


- ✓ **compact** (140 x 260 x 18.5 mm)
- ✓ **light** (1.6 kg)
- ✓ **efficient** ($R_{th} = 8 \text{ }^\circ\text{C/kW}$ @ 5 l/min)
- ✓ **safe and reliable** Leak free (100% tested @ 10 bar)

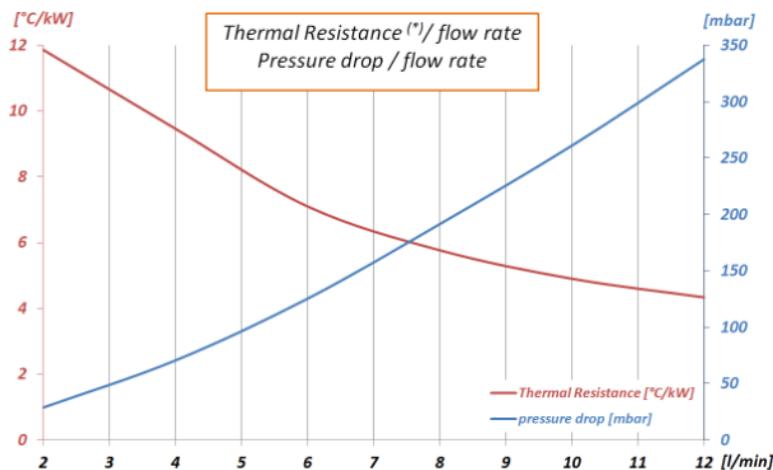
Materials: Aluminum alloy Al EN AW 6060 + turbulators inside

Cooling circuit 100% sealed by brazing under controlled atmosphere

Very uniform temperature distribution under power modules



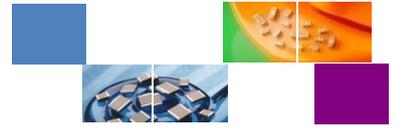
- Compatible Power Module Packages:**
- ✓ MITSUBISHI IGBTMOD™ A, NF & NFH Series
 - ✓ FUJI Semiconductor M238 and M247



Suitable for any high power semiconductor application



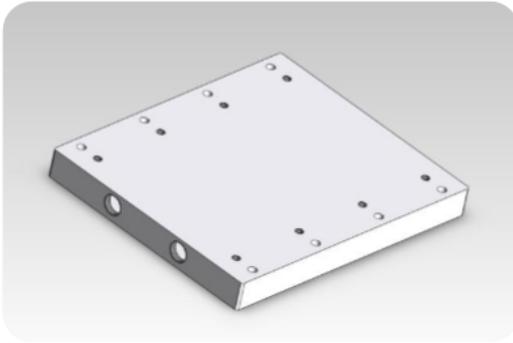
(*) Thermal Resistance: $\max T_{LCP \text{ surface}} \text{ to } T_{\text{fluid IN}}$ (Water + Ethylene Glycol 50% vol. @40°C)



One step ahead in cooling!

STANDARD PT Zed 1518

PRIATHERM

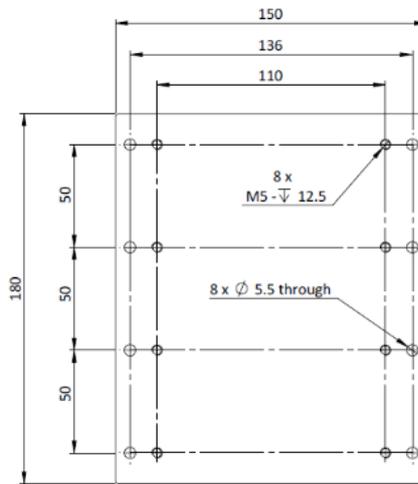


- ✓ **compact** (150 x 180 x 18.5 mm)
- ✓ **light** (1.1 kg)
- ✓ **efficient** ($R_{th} < 10 \text{ } ^\circ\text{C}/\text{kW}$ @ 5 l/min)
- ✓ **safe and reliable** Leak free (100% tested @ 10 bar)

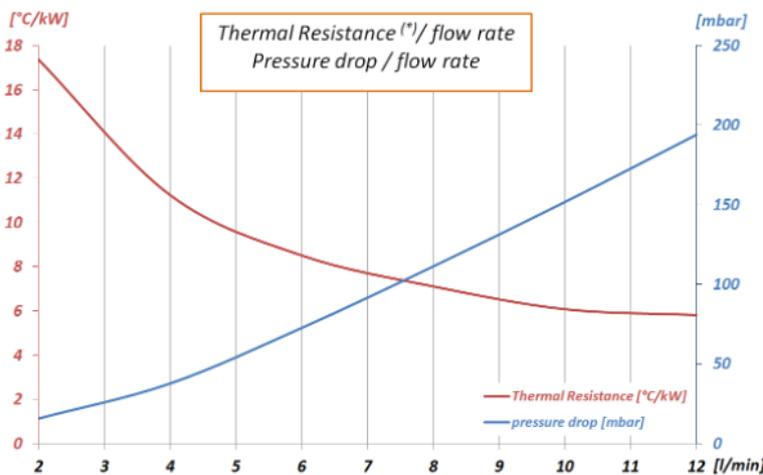
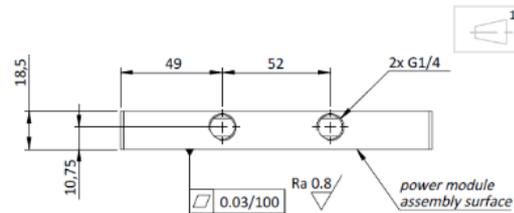
Materials: Aluminum alloy Al EN AW 6060 + turbulators inside

Cooling circuit 100% sealed by brazing under controlled atmosphere

Very uniform temperature distribution under power modules



- Compatible Power Module Packages:**
- ✓ MITSUBISHI Intellimod™ L-Series
 - ✓ INFINEON EconoPACK™ +
 - ✓ SEMIKRON SEMiX® 33
 - ✓ FUJI Semiconductor M629



Suitable for any high power semiconductor application

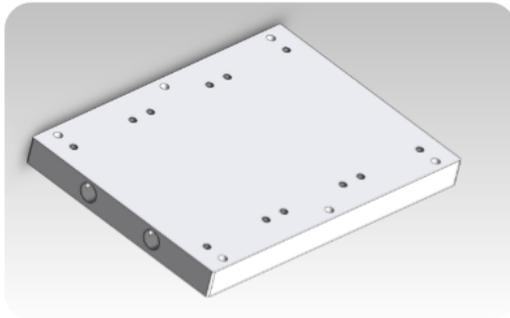


(*) Thermal Resistance: max T_{LCP} surface to $T_{fluid IN}$ (Water + Ethylene Glycol 50%vol. @40°C)



One step ahead in cooling!

STANDARD PT Zed 1521



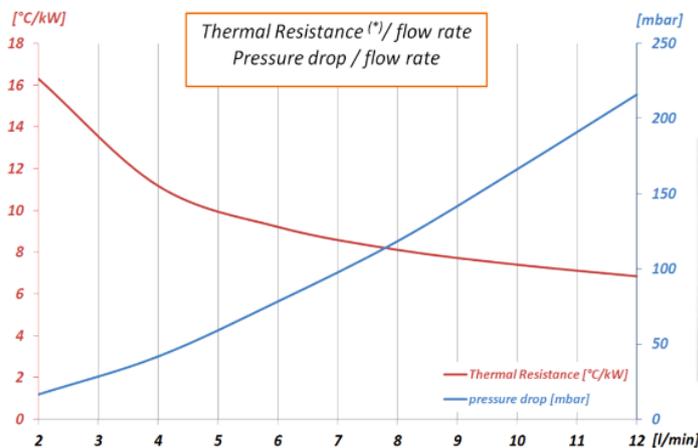
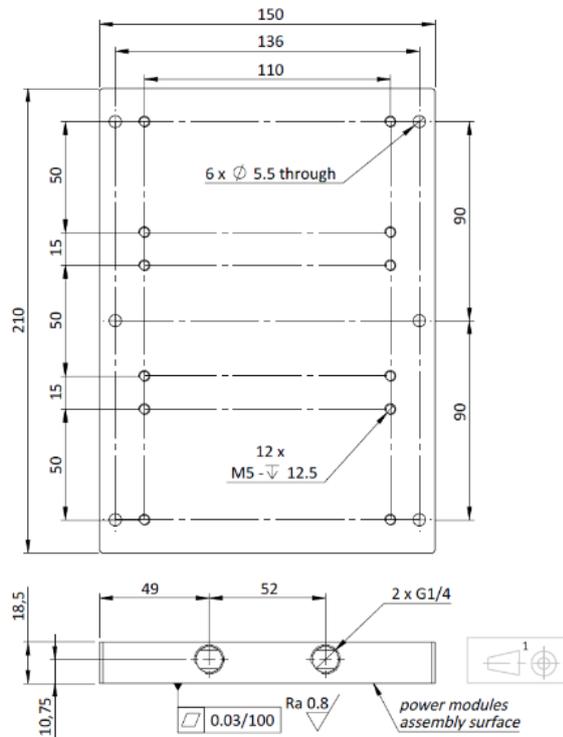
- ✓ **compact** (150 x 210 x 18.5 mm)
- ✓ **light** (1.35 kg)
- ✓ **efficient** ($R_{th} < 10 \text{ }^\circ\text{C/kW}$ @ 5 l/min)
- ✓ **safe and reliable** Leak free (100% tested @ 10 bar)

Materials: Aluminum alloy Al EN AW 6060 + turbulators inside

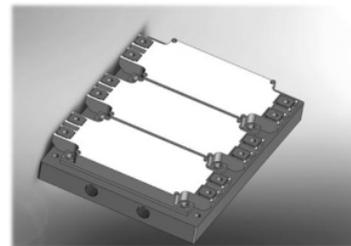
Cooling circuit 100% sealed by brazing under controlled atmosphere

Very uniform temperature distribution under power modules

- Compatible Power Module Packages:**
- ✓ MITSUBISHI IGBTMOD™ A & NX Series
 - ✓ INFINEON EconoDUAL™ 3
 - ✓ SEMIKRON SEMiX® 3
 - ✓ FUJI 122 x 62mm Package



Suitable for any high power semiconductors application



(*) Thermal Resistance: $\max T_{LCP}$ surface to $T_{fluid IN}$ (Water + Ethylene Glycol 50%vol. @40°C)